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4-3-03  
PATENT  
Docket No. 150.00930102  
VS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Eugene P. Marsh ) Group Art Unit: 2823  
Serial No.: 09/812,157 ) Examiner: J. Maldonado  
Confirmation No.: 2941 )  
Filed: March 19, 2001 )  
For: METHODS FOR PATTERNING METAL LAYERS FOR USE WITH  
FORMING SEMICONDUCTOR DEVICES

AMENDMENT & RESPONSE

Assistant Commissioner for Patents  
Box RCE  
Washington D.C. 20231

RECEIVED  
MAR 25 2003  
2800 MAIL ROOM

Dear Sir:

In response to the Office Action of 20 November 2002 and the Advisory Action of 11 February 2003, please consider the amendment and accompanying remarks presented below:

In the Claims

- Please enter and consider new claim 106. The new claim is provided below.

106. (NEW) A method for forming a discontinuous conductive layer, the method comprising:  
providing a substrate assembly having a surface comprising a metal-containing adhesion region and a surface region;  
forming a conductive metal layer on the metal-containing adhesion region and the surface region of the substrate assembly;  
annealing the substrate assembly including the conductive metal layer, whereby the conductive metal layer forms pools of conductive metal material on the surface region of the substrate assembly; and  
removing the pools of conductive metal material from the surface region by rinsing the substrate assembly in a rinsing composition.

03/24/2003 AUONDAF1 00000042 09812157

02 FC:1201 84.00 OP  
03 FC:1202 18.00 OP